

ABOUT US

TechNexion

Established in 1999 TechNexion is an ISO9001 and ISO14001 certified industrial computer manufacturer of CPU Modules and embedded systems featuring RISC/ARM architecture. TechNexion's commitment to provide reliable and high quality manufactured products has given it the reputation to be one of the best companies to work with.

To make TechNexion's solutions accessible to our customers we are continuously training and providing integration guidelines to our global and well established distribution channel. This gives TechNexion the capability to provide direct local service and effectively provide our customers with the latest solution and innovation updates.



Our commitment

We at TechNexion believe that the only way for our customers to put trust in our products is to be as transparent as possible.

Our philosophy is that no matter if your firm is a small engineering design house with few engineers on staff or a large Multinational Corporation, you will require having all product hardware information, documentation and software source code available at your fingertips to make your project successful.

To achieve this, all TechNexion products are backed up with very detailed hardware documentation handbooks, design guides and all source code software which is freely accessible online.











ABOUT US

Quality Control and Assurance

TechNexion is proud to have the best people on the job who understand what quality means to our customers and partners.

From the initial design TechNexion engineers choose only high crafted reliable components that are backed up by renowned brands to ensure product stability and continuous quality. TechNexion ISO9001 and ISO14001 quality assurance systems trace every component being used in our products and guarantees components are kept under optimal conditions.

All products manufactured and assembled by TechNexion are 100% functional tested prior dispatch to our customers to assure all products are conform all specifications.

Customer support

TechNexion products come standard with a smart software loader menu which gives you a variety of software and configuration possibilities. The comprehensive user guides and documentation will assist in further customization and provide valuable information to tailor our modules towards your project needs.

Besides this TechNexion customer support consists of a team of highly professional application engineers who can provide customers with real-time custom project support and assistance.

Research and Development

With a strong world class engineering team and around 50% of TechNexion staff involved in active product research, development, quality assurance and testing, we can assure our customers to work with the latest innovations and guarantee longevity and product availability for up-to 10 years if needed.

Green Computing



As a global citizen TechNexion undertakes an active role in protecting the environment through its compliance with industry and legislation regarding the restriction

on use of lead and other hazardous substances.

It's TechNexion aim to deliver not only the highest grade products but also reduce impact on the environment to an absolute minimum. Not only is this achieved by following the European Union RoHS regulations and Waste Electrical and Electronic Equipment (WEEE) directives but further enforced by a strict ISO14001 system that enforces our suppliers to share the same commitments to protect our environment.



Customization Services

TechNexion offers complete ODM engineering services starting from the brand on a standard product to a complete finished product design. For this we have a well experienced team on staff that can work jointly with customer's unique specifications and requirements.

TechNexion also provides customization services by modifying existing standard products to fit your application requirements such as custom, Software preloading, PCB population modification, enclosure cosmetic branding, packing instructions etc.



Your Truly Global Information Resource

www.technexion.com is your one-stop platform for the latest information on all TechNexion products and services. The rejuvenated website not only contains product relevant information and data, solutions/ products demo, up-to-date news, but incorporates online downloads, publications, and technical service supports.

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LS1021A-IOT





Specifications

System

Processor Technology PMIC Memory Storage **Removable Storage** Operation System

Freescale LS1021A ARM Cortex-A7 Dual core Freescale VR500 PMIC 1GB ECC protected DDR3 1 Gb QSPI NOR Flash SHDC upto 32GB (8GB SD card included) Linux 3.x, Yocto

JTAG Interface by thruhole

1x SDIO / MMC

2x PCIe 2.0

24 bit LVDS

USB OTG 3.0 USB Host 2.0

SPI, I²C, GPIO

2x UART

Connectors

Debug Interface

I/O Interface Signalling 1x SATA III

Storage

Expansion Display USB

CAN Bus Serial Port Other

Network

Network RGMII Network SGMII Network Switch Atheros AR8033 Gigabit LAN PHY Atheros AR8033 Gigabit LAN PHY 4 port gigabit switch

2x Flex CAN version 2.0B Compliant

Main Features

- The LS1021A-IoT gateway reference design based on the Freescale Layerscape LS1021A processor is a purposebuilt, small footprint hardware platform equipped with a wide array of high-speed connectivity and low-speed serial interfaces engineered to support the secure delivery of IoT services to end users in a home, business or other commercial location. The affordable reference design combines standards-based, open source software together with a feature-rich IoT gateway design, to establish a common, open framework for secure IoT service delivery and management.
- This reference design provides a wide assortment of high speed and serial based connectivity in a compact, highly secure design, delivering an impressive level of versatility. High efficiency is achieved through the use of the ARMbased Layerscape LS1021A embedded processor, which delivers over 5,000 Coremarks of performance at a typical power of under 3 Watts. In addition to its outstanding performance efficiency and high level of integration, the LS1021A-IoT gateway design offers HDMI, SATA3 and USB3 connectors as well as a complete Linux software developers package.

Video

Display chipset Silicon Image Sil9022 Display interface HDMI connector

Audio

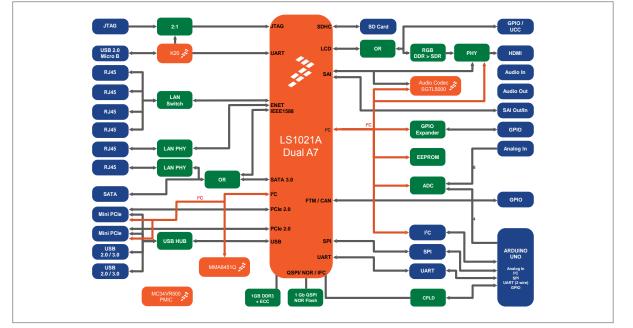
Audio Codec Freescale SGTL5000 Audio connectors Audio In / Out

Power Specifications

Input Power 12VDC

LS1021A-IOT

Block Diagram



Environmental and Mechanical

Temperature Humidity Dimensions

Certification

Weight

Commercial : 0° to 40° C 10 to 90% 200 x 170 x 58 mm 7% x 6% x 2¼ inch 1200 grams Compliant with CE, FCC, RoHS, REACh directives

Ordering Information

LS1021A-IOT

LS1021A-IOT Gateway Reference design. Including power adaptor, HDMI and USB debug cable and 8GB SDHC card

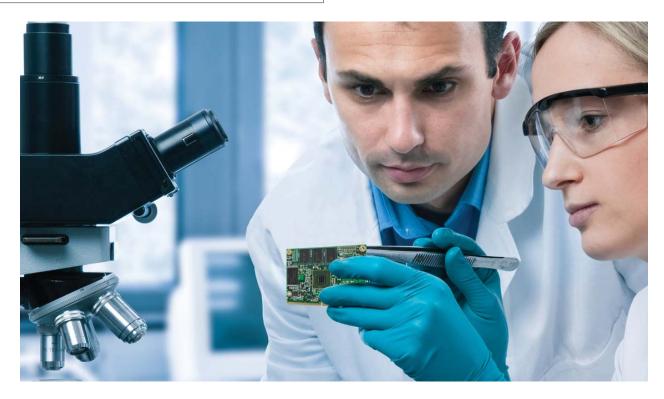
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Evaluation and Development Reference Designs **TechNexion**

EDM STANDARD



How EDM can benefit you

EDM is an open standard under the Creative Commons Share Alike license and is the first true x86/ARM Cross platform pin-to-pin compatible standard covering a wide spectrum of CPU architectures ranging from low power efficient ARM Cortex A7 SoC's all the way up to 64 bit multicore processor modules.

EDM System on Modules (SoM's) are a versatile small form factor computer module providing a flexible solution to OEM's that require a scalable low power modular computing solution.

Why should you choose EDM Modules?

EDM modules provide complete building blocks including memory, boot flash, power sequencing, CPU power supplies, Ethernet, wireless communication interfaces and graphic engine cores on the module.

EDM modules are used in conjunction with carrier boards that implement application specific features such as audio codecs, display and touch solutions and communication and control interfaces to external devices.

The EDM specifications and design guides for carrier boards as well as the schematics for the Evalution boards are completely open-source.



For more information about the EDM Standard. Visit **www.edm-standard.org**

EDM Form Factors



Longevity

TechNexion EDM Modules incorporate only components from embedded roadmaps of strategic suppliers and are backed up with value added technical services such as life cycle management, revision control and end-of-life support.

TechNexion and Open Source

TechNexion EDM modules come standard with source code and binary demo images for the following Operating Systems.



Android binary demo images, instructions to make your own as well as complete source code available.



Linux binary demo images and full source code u-boot, kernel and support packages available.

yocto yocto binary demo images and full source code u-boot, kernel and support packages available.

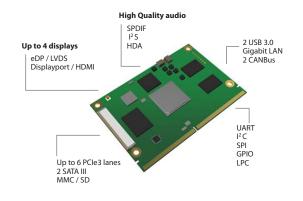


ubuntu binary demo images available.

Development Startkits

Kickstart your project development cycle with our plug and play development startkits that come pre-loaded with working software and all tools to assist you to validate performance and explore additional possibilities without the need to invest a huge amount of time and resources upfront.

EDM interfaces overview



Custom Carrier board Design

Customers can design their own carrier board using the freely available schematic design files and leverage on the available software source code that comes standard with every EDM Module and therefore bringing a custom designed solution to market using a very short design cycle and reduced engineering risks.

TechNexion offers custom tailored carrier board design and manufacturing services where our expertise as co-founder of the EDM standard will assist you to ensure your design is fully compatible and future upgrade proof while moving to next generation EDM modules.

						E	DM Type	1							
Power	LAN		TTL		GPM	С	I ² S 2 nd	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD	
5 VDC		LVDS/ eDP 1 st	HDMI/ DP 1 st	PCle x2	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2		x2	l²C x2	+ GPIO	RTC	

						E	DM Type	2						
Power	LAN	LVDS/ eDP 2 nd	HDMI/ DP 2 nd	PCle x4	SATA 2 nd	LPC	HDA	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC		LVDS/ eDP 1 st	HDMI/ DP 1 st	PCle x2	SATA 1 st	USB OTG	USB Host	I²S 1 st	x2	30	x2	l ² C x2	+ GPIO	RTC

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OVERVIEW



Model Name	EDM1-CF-iMX6	EDM1-CF-iMX6SX	EDM1-CF-LS1021A	EDM1-CF-iMX6UL	EDM2-CF-iMX6
Signalling		ED	M1		EDM2
Technology	ARM Cortex A9	ARM Cortex A9 + M4	ARM Cortex A7	ARM Cortex A7	ARM Cortex A9
Processor	1-2-4 Core	Single Core	Dual Core	Single Core	1-2-4 Core
System Memory	up to 2GB DDR3	up to 2GB DDR3	up to 2GB DDR3 + ECC	up to 1GB DDR3	up to 2 GB DDR3
Storage	eMMC	eMMC	NAND	QSPI	eMMC
FPC Connector	MIPI CSI / DSI	ADC Signals			MIPI CSI / DSI
JTAG Interface	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Bluetooth	BT v. 4.0	BT v. 4.0		BT v. 4.0	BT v. 4.0
Wireless LAN	2.4Ghz 802.11bgn	2.4Ghz 802.11bgn		2.4Ghz 802.11ac	2.4Ghz 802.11bgn
Network	Gigabit LAN	2 Gigabit LAN	2 Gigabit LAN	2 LAN	Gigabit LAN
HDMI	\checkmark		EDM1-CF-LS1021A-H		\checkmark
LVDS	1 channel LVDS	1 channel LVDS	EDM1-CF-LS1021A-L	1 channel LVDS	2 channel LVDS
TTL	\checkmark	\checkmark		\checkmark	
l²S	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
PCle	1 x PCle 2.0	1 x PCle 2.0	2 x PCIe 2.0		1 x PCle 2.0
SATA	1x SATA 2.0		1x SATA 3.0		1x SATA 2.0
USB Host	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
USB OTG	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
SDIO	1	1	1	1	1
CAN Bus	2	2	2	2	2
UART	2	2	2	2	2
SPI	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
l ² C	\checkmark	\checkmark	✓	\checkmark	\checkmark
GPIO	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Dimensions	82 x 60mm 35⁄k x 2¾ inch	82 x 60mm 35% x 2⅔ inch	82 x 60mm 35% x 2⅔ inch	82 x 60mm 35∕s x 2¾ inch	82 x 60mm 35⁄8 x 2⅔ inch

EDM Standard SOM's and Carrier Boards



Model Name	EDM1-FAIRY	EDM1-GOBLIN	EDM2-ELF	EDM2-WIZARD
System on Module	EDM Type 1 compact	EDM Type 1 compact	EDM Type 2 compact	EDM Type 2
Mini PCle	2	2	2	2
HDMI	1	1	1	2
LVDS	1 channel	1 channel	2 channel	2 channel
TTL	\checkmark	\checkmark		
SATA	1	1	1	2
SD cardslot	μSD	μSD	μSD	SD
Gigabit LAN	1	2	1	1
USB Host	2	2	2	2
USB OTG	1	1	1	1
UART	2	2	2	2
CAN Bus	2	2	2	2
SPI	2	2	2	2
GPIO	8	8	8	8
l ² C	2	2	2	2
l²S	2	2	2	2
Audio Connector	\checkmark	\checkmark	\checkmark	\checkmark
Speaker	2W	2W	2W	2W
Touch Controller	4 wire touch	4 wire touch	4 wire touch	4 / 5 wire touch
3-axis Movement	\checkmark	\checkmark	\checkmark	
Light Sensor	\checkmark	\checkmark	\checkmark	
Compass	\checkmark	\checkmark	\checkmark	
Real Time Clock	\checkmark	\checkmark	\checkmark	
Input Power	12 VDC	12 VDC	12 VDC	10~30 VDC
Form Factor	3.5″	3.5″	3.5″	Micro ATX
Dimensions	147 x 102 mm 5¾ x 4 inch	147 x 102 mm 5¾ x 4 inch	147 x 102 mm 5¾ x 4 inch	244 x 244 mm 9% x 9% inch

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EDM Standard SOM's and Carrier Boards **TechNexion**

CORPORATE

EVM

DUCAN

EDM1-CF-IMX6



Main Features

- ARM Cortex-A9 Freescale i.MX6 scalable single/dual/ quad core EDM type 1 compact System-on-Module
- Gigabit LAN, WiFi 802.11 b/g/n and Bluetooth v. 4.0 communication interface
- Targeting multimedia applications with LVDS, TTL, HDMI, S/PDIF, I²S, MIPI camera and display



Real Time OS

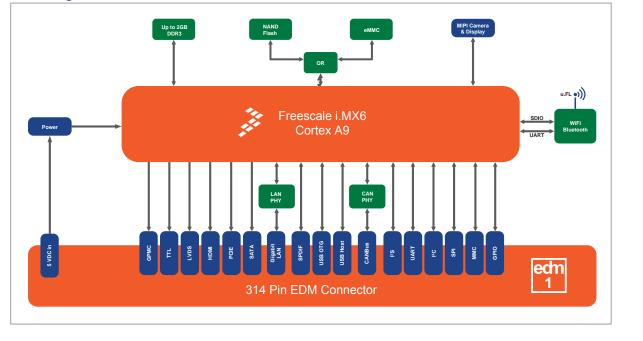
Power	LAN	πι			GPMC		I ² S 2 nd SPDIF		CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC	LAN	LVDS	ндмі	PCle x1	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	30	x2	l ² C x2	+ GPIO	RTC

Specifications

Core System		Video		
Signalling	EDM Type 1 compliant	VIGEO	Solo / Duallite	Dual / Quad
CPU	Freescale i.MX6Quad @ 1Ghz	GPU 3D	Vivante GC880	Vivante GC2000
	Freescale i.MX6Dual @ 1Ghz		35Mtri/s 266Mpxl/s	200Mtri/s 1000Mpxl/s
	Freescale i.MX6DualLite @ 1Ghz		Open GL ES 2.0	OpenGL ES 2.0
	Freescale i.MX6Solo @ 1Ghz			& Halti, CL EP
System Memory	up to 2GB DDR3			
Storage	eMMC (default 4GB)	GPU 2D	emulated on GPU 3D	Vivante GC355
	optional NAND Flash (MOQ apply)	(Vector Graphics)		300Mpxl/s
Debug Interface FPC Connector	JTAG Interface by thruhole MIPI Interface Camera			OpenVG 1.1
FPC Connector	MIPI Interface Camera MIPI Interface Display	GPU 2D	Vivante GC320	Vivante GC320
Connectivity	Mir I interface Display	(Composition)	600MpxI/s, BLIT	600MpxI/s, BLIT
Network	Atheros AR8031 Gigabit LAN	(composition)	000101px1/3, DEI1	000101px1/3, DEI1
WiFi	Broadcom BCM4330 802.11bgn	Video Decode	1080p30 + D1	1080p60 H.264
Bluetooth	Broadcom BCM4330 BT 4.0	Video Encode	1080p30 H.264	1080p30 H.264
			BP / Dual 720p	BP / Dual 720p
I/O Interfaces				
Storage	1x SATA 2.0 (Dual /Quad only)	Audio		
	1x SDIO / MMC	Interface	I ² S (2 channel), S/PDIF	
Expansion	1x PCle 2.0	Audio Codec	on EDM Carrier Board	
Display	HDMI v1.4 1 channel LVDS 18/24 bit	Power Specific	ations	
	24 bit RGB TTL	Input power	5 VDC +/- 5%	
USB	USB Host 2.0	input power	5 VDC +7- 5%	
050	USB OTG 2.0	Operation Syst	ems	
CAN Bus	2x Flex CAN version 2.0B compliant	Standard Support	Linux	
Serial Port	2x UART		Android	
Other	SPI, I ² C, I ² S, GPIO, Local Bus (GPMC)	Extended Support	Commercial Linux	
			Windows Embedded C	ompact

EDM1-CF-IMX6





Environmental and Mechanical

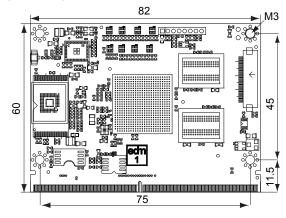
Temperature

Humidity Module Connector Form Factor Dimensions

MTBF Weight Shock Vibration Commercial : 0° to 60° C Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 314 pins MXM3 EDM Compact Form Factor 82 x 60 mm (3% x 2% inch) >100,000 hours 20 grams 50G / 25ms 20G / 0-600 Hz

Dimensions

(units in mm)



Ordering Information

EDM1-CF-IMX6S10-R512-NI4G-L-2C EDM Compact Type 1 Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB eMMC+ Gigabit LAN + 2 CAN EDM1-CF-IMX6U10-R1GB-NI4G-L-2C EDM Compact Type 1 Freescale i.MX6 Duallite 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN EDM1-CF-IMX6D10-R1GB-NI4G-L-S-2C EDM Compact Type 1 Freescale i.MX6 Dual 1Ghz + 1GB RAM +

4GB eMMC + Gigabit LAN + 2 CAN + SATA EDM1-CF-IMX6Q10-R2GB-NI4G-L-S-2C EDM (compact Turne 1 Excessed in MX6 Quind 1 Chr. + 2CB DAM +

EDM Compact Type 1 Freescale i.MX6 Quad 1Ghz + 2GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA **EDM1-CF-IMX6S10-R512-NI4G-BW-L-2C**

EDM Compact Type 1 Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + 802.11bgn + Bluetooth 4.0 EDM1-CF-IMX6U10-R1GB-NI4G-BW-L-2C

EDM Compact Type 1 Freescale i.MX6 Duallite 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + 802.11bgn + Bluetooth 4.0 EDM1-CF-IMX6D10-R1GB-NI4G-BW-L-S-2C

EDM Compact Type 1 Freescale i.MX6 Dual 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA + 802.11bgn + Bluetooth 4.0 EDM1-CF-IMX6Q10-R2GB-NI4G-BW-L-S-2C

EDM Compact Type 1 Freescale i.MX6 Quad 1Ghz + 2GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA + 802.11bgn + Bluetooth 4.0

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EDM1-CF-IMX6SX



Main Features

- ARM Cortex-A9 Single core + ARM Cortex M4 Freescale i.MX6 SoloX EDM Type 1 compact System-on-Module.
- Dual gigabit LAN and optional WiFi/BT connectivity.
- Support for Android, Linux, Yocto and MQX realtime OS



Power	LAN	TTL			2 nd LAN		I ² S 2 nd SPDIF		CANBus	SD	SPI	UART x2	F Buttons + GPIO	RSVD
5 VDC		LVDS	HDMI	PCle x1	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2		x2	l²C x2	+ GPIO	RTC

Specifications

Core System

CPU

PMIC

Storage

Signalling EDM Type 1 compliant Freescale i.MX6SoloX @ 1Ghz Technology ARM Cortex-A9 single core + ARM Cortex M4 Freescale MMPF0100 System Memory up to 2GB DDR3 eMMC (default 4GB) QSPI (default 256MB) optional NAND Flash (MOQ apply) Debug Interface JTAG Interface by thruhole **FPC Connector** ADC Signals

Two (2) Atheros AR8031 Gigabit LAN

Broadcom BCM4330 802.11bgn

Broadcom BCM4330 BT 4.0

Connectivity

Network WiFi Bluetooth

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I/O Interfaces

Storage 1x SDIO / MMC Expansion 1x PCle 2.0 1 channel LVDS 18/24 bit Display 24 bit RGB TTL USB USB Host 2.0 USB OTG 2.0 CAN Bus 2x Flex CAN version 2.0B compliant Serial Port 2x UART Other SPI, I²C, I²S, GPIO

Video

GPU 3D PXP

Vivante GC400T 17Mtri/s 133Mpxl/s Open GL ES 2.0 Image re-sizing, rotation, overlay and CSC Pixel Processing Pipeline

I²S (2 channel), S/P DIF

on EDM Carrier Board

Audio

Interface Audio Codec

Power Specifications

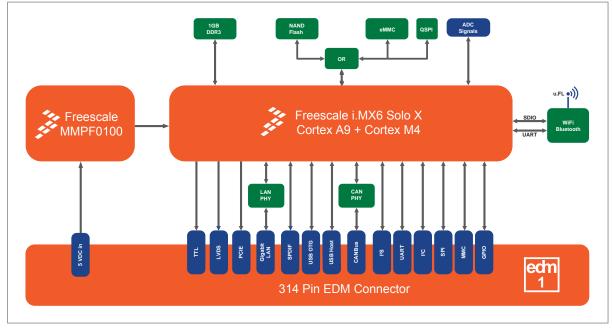
5 VDC +/- 5% Input power

Operation Systems

Standard Support Linux Yocto Android **Commercial Linux** Extended Support Windows Embedded Compact Real Time OS

EDM1-CF-IMX6SX





Environmental and Mechanical

Commercial : 0° to 60° C Temperature Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) Humidity 10 to 90% Module Connector 314 pins MXM3 Form Factor EDM Compact Form Factor Dimensions 82 x 60 mm (3⁵/₈ x 2³/₈ inch) MTBF >100,000 hours Weight 20 grams Shock 50G / 25ms 20G / 0-600 Hz Vibration

Ordering Information

EDM1-CF-IMX6X10-R1GB-NI4G-2L-2C

EDM Compact Type 1 Freescale i.MX6 SoloX 1Ghz + 1GB DDR3 + 4GB eMMC + 2 Gigabit LAN + 2 CAN

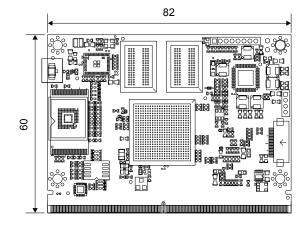
EDM1-CF-IMX6X10-R1GB-NI4G-BW-2L-2C EDM Compact Type 1 Freescale i.MX6 SoloX 1Ghz + 1GB DDR3 +

4GB eMMC + Gigabit LAN + 2 CAN + 802.11bgn + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions

(units in mm)



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CORPORATE

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EDM Standard SOM's and Carrier Boards **TechNexion**

EDM1-CF-IMX6UL



Main Features

- ARM Cortex-A7 Single core Freescale i.MX6UL EDM Type 1 compact System-on-Module
- Optional WiFi/BT connectivity.
- Support for Android, Linux, Yocto and realtime OS



Power	LAN		TTL		2 nd LA	N	l ² S 2 nd	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC		LVDS	HDMI	PCle x1	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2		x2	l²C x2	+ GPIO	RTC

Specifications

Core System

Signalling CPU Technology PMIC System Memory Storage Debug Interface EDM Type 1 compliant Freescale i.MX6UL @ 528MHz ARM Cortex-A7 single core Freescale MMPF3000 up to 1GB DDR3 QSPI (default 256MB) optional NAND Flash (MOQ apply) JTAG Interface by thruhole

Connectivity

Network2x Fast EthernetWiFiBroadcom BCM4335 802.11acBluetoothBroadcom BCM4335 BT 4.0

I/O Interfaces

Storage	1x SDIO / MMC
Display	1 channel LVDS 18/24 bit
	24 bit RGB TTL
USB	USB Host 2.0
	USB OTG 2.0
CAN Bus	2x Flex CAN version 2.0B compliant
Serial Port	2x UART
Other	SPI, I ² C, I ² S, GPIO

Video

PXP

- - - -

Audio

Interface Audio Codec

Power Specifications

Input power 5 VDC +/- 5%

Operation Systems

Standard Support Extended Support Linux Yocto Commercial Linux Windows Embedded Compact Real Time OS

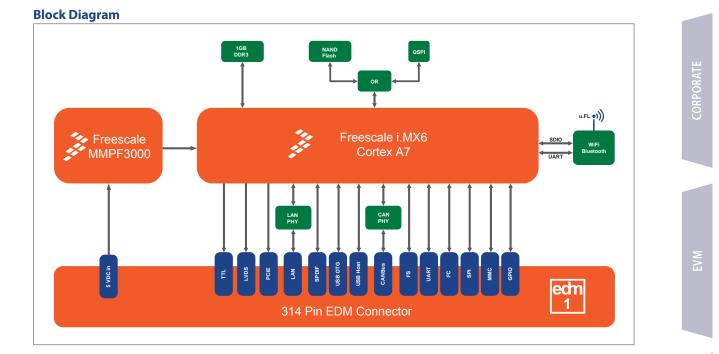
Image re-sizing, rotation, overlay and

CSC Pixel Processing Pipeline

I²S (2 channel), S/P DIF

on EDM Carrier Board

EDM1-CF-IMX6UL



Environmental and Mechanical Temperature Commercial: 0° to 60° C

Exte Indu Humidity 10 tr Module Connector 314 Form Factor EDM Dimensions 82 x (35% MTBF >100 Weight 20 g

MTBF Weight Shock Vibration Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 314 pins MXM3 EDM Compact Form Factor 82 x 60 mm (3% x 2% inch) >100,000 hours 20 grams 50G / 25ms 20G / 0-600 Hz

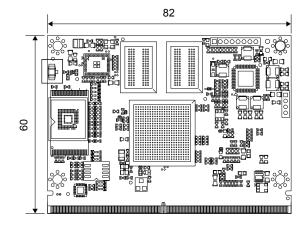
Ordering Information

TBD.

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions

(units in mm)



2015-05. All specifications are subject to change without notice.

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TOUCAN

EDM

EDM1-CF-LS1021A



Main Features

- Freescale QorlQ LS1021A EDM Type 1 System on Module for network and security applications.
- Dual gigabit LAN, 2 PCI Express, SATA III and USB 3.0 connectivity.
- Harsh environment friendly with DDR3 **ECC** protection.



Power	LAN		TTL		2 nd LAN		I ² S 2 nd SPDIF		CANBus	SD	SPI	UART x2	Buttons + GPIO	RSVD
5 VDC	LAN	LVDS	HDMI	PCle x2	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	50	x2	l ² C x2	+ GPIO	RTC

Specifications

Core System

Signalling CPU Technology System Memory PMIC Storage Debug Interface EDM Type 1 compliant Freescale QorlQ LS1021A @ 1Ghz ARM Cortex-A7 dual core up to 2GB DDR3 with **ECC** protection Freescale VR500 NAND Flash JTAG Interface by thruhole

RGMII Atheros AR8033 Gigabit LAN

SGMII Atheros AR8033 Gigabit LAN

Connectivity

Network

I/O Interfaces

1x SATA 3.0 Storage 1x SDIO / MMC 2x PCle 2.0 Expansion Display HDMI (EDM1-CF-LS1021A-H only) 1 channel LVDS (EDM1-CF-LS1021A-L only) USB USB Host 2.0 USB OTG 3.0 CAN Bus 2x Flex CAN version 2.0B compliant Serial Port 2x UART SPI, I²C, I²S, GPIO Other

Video

LVDS Transmitter HDMI Transmitter

DS90C387 (EDM1-CF-LS1021A-L only) Sil9022(EDM1-CF-LS1021A-H only)

Audio

InterfaceI²S (1 channel)Audio CodecOn EDM Carrier Board

Power Specifications

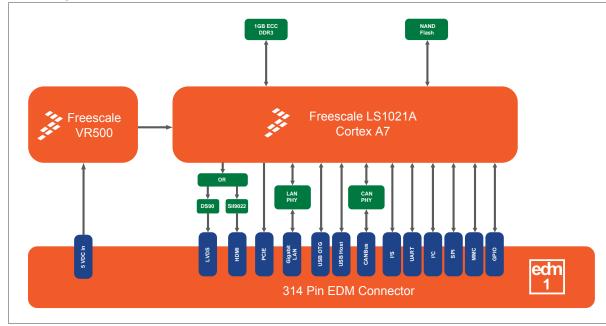
Input Power 5 VDC +/- 5%

Operation Systems

Standard Support	Linux
	Yocto
Extended Support	Windows Embedded Compact
	Real Time OS

EDM1-CF-LS1021A

Block Diagram



Environmental and Mechanical

Environnentaria	meenamean
Temperature	Commercial : 0° to 60° C
	Extended : -20° to 70° C
	Industrial : -40° to 85° C
Humidity	10 to 90%
Module Connector	314 pins MXM3
Form Factor	EDM Compact Form Factor
Dimensions	82 x 60 mm
	(35∕‰ x 23⁄‰ inch)
MTBF	>100,000 hours
Weight	20 grams
Shock	50G / 25ms
Vibration	20G / 0-600 Hz

Ordering Information

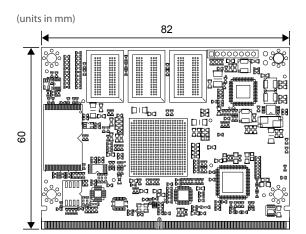
EDM1-CF-LS1021A-L-R1GE-N512-2L-2C EDM Compact Type 1 Freescale QorlQ LS1021A 1Ghz + LVDS Display + 1GB ECC Protected DDR3 + 512MB NAND Flash + 2 Gigabit LAN + 2 CAN

EDM1-CF-LS1021A-H-R1GE-N512-2L-2C

EDM Compact Type 1 Freescale QorlQ LS1021A 1Ghz + HDMI Display + 1GB ECC Protected DDR3 + 512MB NAND Flash + 2 Gigabit LAN + 2 CAN

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions



2015-05. All specifications are subject to change without notice.

EDM2-CF-IMX6



Main Features

- ARM Cortex-A9 Freescale i.MX6 scalable single/dual/ quad core EDM type 2 compact System-on-Module
- Gigabit LAN, WiFi 802.11 b/g/n and Bluetooth v. 4.0 communication interface
- Targeting multimedia applications with LVDS, HDMI, S/PDIF, I²S, MIPI camera and display



Real Time OS

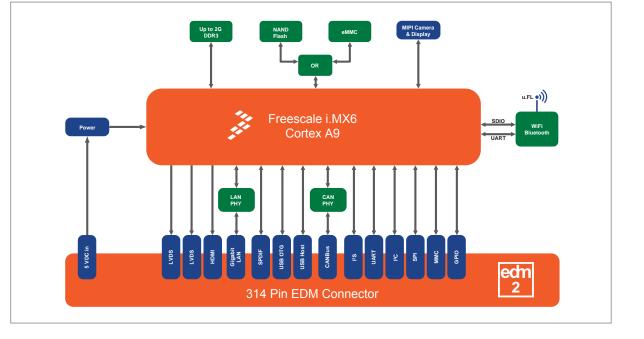
Power	LAN	LVDS	HDMI	PCle x4	SATA 2 nd	LPC	HDA	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC		LVDS	HDMI	PCle x1	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	30	x2	l²C x2	+ GPIO	RTC

Specifications

Core System		Video		
Signalling	EDM Type 2 compliant		Solo / Duallite	Dual / Quad
CPU	Freescale i.MX6Quad @ 1Ghz	GPU 3D	Vivante GC880	Vivante GC2000
	Freescale i.MX6Dual @ 1Ghz		35Mtri/s 266Mpxl/s	200Mtri/s 1000Mpxl/s
	Freescale i.MX6DualLite @ 1Ghz		Open GL ES 2.0	OpenGL ES 2.0
	Freescale i.MX6Solo @ 1Ghz			& Halti, CL EP
System Memory	up to 2GB DDR3			
Storage	eMMC (default 4GB)	GPU 2D	emulated on GPU 3D	Vivante GC355
	optional NAND Flash (MOQ apply)	(Vector Graphics)		300Mpxl/s
Debug Interface	JTAG Interface by thruhole			OpenVG 1.1
FPC Connector	MIPI Interface Camera			
	MIPI Interface Display	GPU 2D	Vivante GC320	Vivante GC320
Compositivity		(Composition)	600Mpxl/s, BLIT	600Mpxl/s, BLIT
Connectivity				
Network WiFi	Atheros AR8031 Gigabit LAN	Video Decode	1080p30 + D1	1080p60 H.264
Bluetooth	Broadcom BCM4330 802.11bgn Broadcom BCM4330 BT 4.0	Video Encode	1080p30 H.264 BP / Dual 720p	1080p30 H.264 BP / Dual 720p
Bluetooth	DIOGOCOTTI DCIM4550 BT 4.0		BP / Dual / 20p	BP / Dual / 20p
I/O Interfaces		Audio		
Storage	1x SATA 2.0 (Dual /Quad only)	Interface	I ² S (2 channel), S/PDIF	
	1x SDIO / MMC	Audio Codec	on EDM Carrier Board	
Expansion	1x PCIe 2.0			
Display	HDMI v1.4	Power Specific		
	2 channel LVDS 18/24 bit	Input power	5 VDC +/- 5%	
USB	USB Host 2.0			
	USB OTG 2.0	Operation Syst		
CAN Bus	2x Flex CAN version 2.0B compliant	Standard Support	Linux	
Serial Port	2x UART	F i i i c i	Android	
Other	SPI, I²C, GPIO	Extended Support	Commercial Linux	
			Windows Embedded C	ompact

EDM2-CF-IMX6

Block Diagram



Environmental and Mechanical

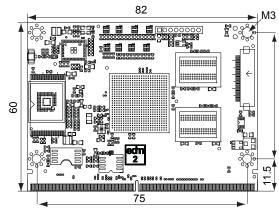
Temperature

Humidity Module Connector Form Factor Dimensions

MTBF Weight Shock Vibration Commercial : 0° to 60° C Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 314 pins MXM3 EDM Compact Form Factor 82 x 60 mm (3% x 2% inch) >100,000 hours 20 grams 50G / 25ms 20G / 0-600 Hz

Dimensions

(units in mm)



Ordering Information

EDM2-CF-IMX6S10-R512-NI4G-L-2C EDM Compact Type 2 Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB eMMC+ Gigabit LAN + 2 CAN EDM2-CF-IMX6U10-R1GB-NI4G-L-2C EDM Compact Type 2 Freescale i.MX6 Duallite 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN EDM2-CF-IMX6D10-R1GB-NI4G-L-S-2C EDM Compact Type 2 Freescale i.MX6 Dual 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA EDM2-CF-IMX6Q10-R2GB-NI4G-L-S-2C

EDM Compact Type 2 Freescale i.MX6 Quad 1Ghz + 2GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA

EDM2-CF-IMX6S10-R512-NI4G-BW-L-2C EDM Compact Type 2 Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + 802.11bgn + Bluetooth 4.0 EDM2-CF-IMX6U10-R1GB-NI4G-BW-L-2C

EDM Compact Type 2 Freescale i.MX6 Duallite 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + 802.11bgn + Bluetooth 4.0 EDM2-CF-IMX6D10-R1GB-NI4G-BW-L-S-2C

EDM Compact Type 2 Freescale i.MX6 Dual 1Ghz + 1GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA + 802.11bgn + Bluetooth 4.0 EDM2-CF-IMX6Q10-R2GB-NI4G-BW-L-S-2C

EDM Compact Type 2 Freescale i.MX6 Quad 1Ghz + 2GB RAM + 4GB eMMC + Gigabit LAN + 2 CAN + SATA + 802.11bgn + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.

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2015-05. All specifications are subject to change without notice.

EDM1-FAIRY



Main Features

- Develop your mobile embedded device quickly with the Fairy EDM Carrier Board which features a variety of sensors and interconnects.
- HDMI, TTL and LVDS display interfaces.
- Communication by dual PCI Express (with SIM cardslots).
- Dual CAN Bus, Dual UART, USB and 8 GPIO's for Industrial control.



1x HDMI

S/PDIF

RGB TTL 24 bit

Jumper selectable: Freescale SGTL5000 (I²S),

TI TLV320AIC23B (I2S)

1x 3.5 mm jack Stereo Audio in

1x 3.5 mm jack Microphone

TSC2046 (4 wire by SPI)

4 wire touch panel

1x 3.5 mm jack Stereo Audio out

2W amplified speaker connectors

1 channel LVDS 18/24 bit

Power	LAN		TTL		GPM	c	I ² S 2 nd	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
12 VDC		LVDS	HDMI	PCle x2	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	30	x2	l ² C x2	+ GPIO	RTC

Specifications

Core System System on Module

Expansion

Expansion Slots

I/O Interfaces

Connector

Header

EDM Type 1 compact form factor

2x mini-PCle + SIM cardslot (for 3G communication)

1x SATA 1x micro SD cardslot (SDIO) 1x Gigabit LAN 2x USB 3.0 Host 1x micro USB 3.0 / 2.0 OTG 1x UART (RS-232/422/485) 2x CAN Bus 1x UART (RS-232) 2x SPI 8x GPIO 2x I²C GPMC Header Manufacturing pins

Video

Connector

Audio Codec

Connector

Speaker

Touch Controller

Connector

Sensors

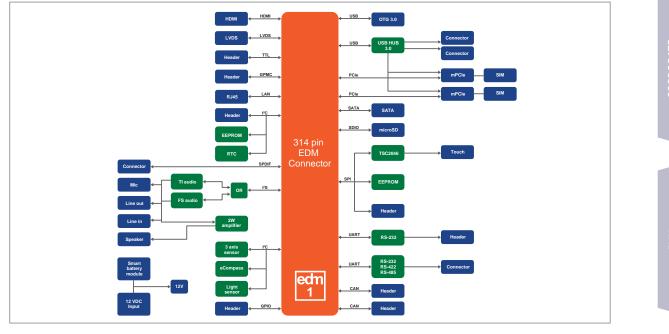
3-axis Movement Light Sensor Compass Real Time Clock ST Microelectronics LIS331DLH Intersil ISL29023IROZ-T7 Freescale MAG3110FCR1 Maxim integrated DS1337+

Power Specifications

Input power Battery 12 VDC Smart battery connector

EDM1-FAIRY

Block Diagram



Environmental and Mechanical Commercial : 0° to 60° C

Temperature

Weight

Shock

Vibration

Humidity Module Connector Form Factor Dimensions MTBF

Industrial : -40° to 85° C 10 to 90% 314 pins MXM3 3.5" Form Factor 147 x 102 mm (5¾ x 4 inch) >100,000 hours 115 grams 50G / 25ms 20G / 0-600 Hz

Extended : -20° to 70° C

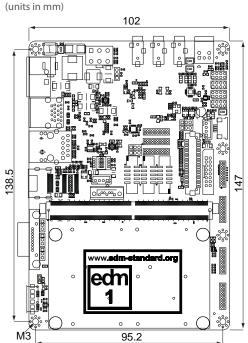
Ordering Information

EDM1-FAIRY 3.5 inch form factor Fairy carrier board for EDM type 1 system-on-modules EDM1-FAIRY-START Fairy EDM type 1 evaluation board

including cablekit and adaptor

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions



2015-05. All specifications are subject to change without notice.

EDM1-GOBLIN



Main Features

- Develop your mobile embedded device quickly with the Goblin EDM Carrier Board which features a variety of sensors and interconnects.
- HDMI, TTL and LVDS display interfaces.
- Communication by dual PCI Express (with SIM cardslots).
- Dual CAN Bus, Dual UART, USB and 8 GPIO's for Industrial control.



1x HDMI

S/PDIF

RGB TTL 24 bit

Jumper selectable:

TI TLV320AIC23B (I2S)

TSC2046 (4 wire by SPI)

4 wire touch panel

1 channel LVDS 18/24 bit

Freescale SGTL5000 (I²S),

1x 3.5 mm jack Stereo Audio in

1x 3.5 mm jack Stereo Audio out 1x 3.5 mm jack Microphone

2W amplified speaker connectors

Power	LAN		TTL		2 nd LA	N	l ² S 2 nd	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
12 VDC		LVDS	ндмі	PCle x2	SATA 1 st	USB OTG	USB Host	l ² S 1 st	x2	30	x2	l ² C x2	+ GPIO	RTC

Specifications

Core System System on Module

Expansion

Expansion Slots

I/O Interfaces

Connector

Header

EDM Type 1 compact form factor

2x mini-PCle + SIM cardslot (for 3G communication)

1x SATA 1x micro SD cardslot (SDIO) 2x Gigabit LAN 2x USB 3.0 Host 1x micro USB 3.0 / 2.0 OTG 1x UART (RS-232/422/485) 2x CAN Bus 1x UART (RS-232) 2x SPI 8x GPIO 2x I²C GPMC Header Manufacturing pins

Video Connector

Audio Codec

Connector

Speaker

Touch Controller Connector

Sensors

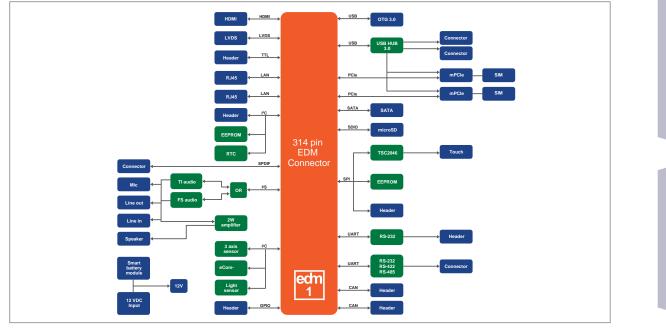
3-axis Movement Light Sensor Compass Real Time Clock ST Microelectronics LIS331DLH Intersil ISL29023IROZ-T7 Freescale MAG3110FCR1 Maxim integrated DS1337+

Power Specifications

Input power Battery 12 VDC Smart battery connector

EDM1-GOBLIN

Block Diagram



Environmental and Mechanical Commercial : 0° to 60° C

Temperature

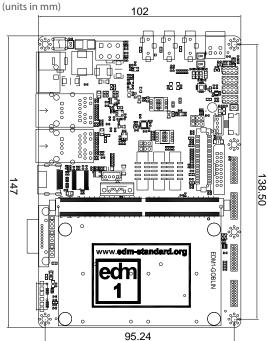
Extended : -20° to 70° C Industrial : -40° to 85° C 10 to 90% Humidity Module Connector 314 pins MXM3 Form Factor 3.5" Form Factor Dimensions 147 x 102 mm (5¾ x 4 inch) MTBF >100,000 hours Weight 115 grams 50G / 25ms Shock Vibration 20G / 0-600 Hz

Ordering Information

EDM1-GOBLIN 3.5 inch form factor Goblin carrier board for EDM type 1 system-on-modules EDM1-GOBLIN-START Goblin EDM type 1 evaluation board including cablekit and adaptor

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions



2015-05. All specifications are subject to change without notice.

EDM2-ELF



Main Features

- Develop your mobile embedded device quickly with the Elf EDM Carrier Board which features a variety of sensors and interconnects.
- HDMI, TTL and LVDS display interfaces.
- Communication by dual PCI Express (with SIM cardslots).
- Dual CAN Bus, Dual UART, USB and 8 GPIO's for Industrial control.



1x HDMI

S/PDIF

2 channel LVDS 18/24 bit

Jumper selectable: Freescale SGTL5000 (I²S),

TI TLV320AIC23B (I²S)

1x 3.5 mm jack Stereo Audio in

1x 3.5 mm jack Microphone

TSC2046 (4 wire by SPI)

Intersil ISL29023IROZ-T7

Freescale MAG3110FCR1

Maxim integrated DS1337+

4 wire touch panel

1x 3.5 mm jack Stereo Audio out

2W amplified speaker connectors

ST Microelectronics LIS331DLH

Power	LAN	LVDS	HDMI	PCle x4	SATA 2 nd	LPC	HDA	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC		LVDS	HDMI	PCle x2	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	30	x2	l²C x2	+ GPIO	RTC

Specifications

Core System

System on Module

Expansion

Expansion Slots

I/O Interfaces

Connector

Header

EDM Type 2 compact form factor

2x mini-PCle + SIM cardslot (for 3G communication)

1x SATA 1x micro SD cardslot (SDIO) 1x Gigabit LAN 2x USB 3.0 Host 1x micro USB 3.0 / 2.0 OTG 1x UART (RS-232/422/485) 2x CAN Bus 1x UART (RS-232) 2x SPI 8x GPIO 2x I²C Manufacturing pins Video Connector

Audio Codec

Connector

Speaker

Touch

Controller Connector

Sensors

3-axis Movement Light Sensor Compass Real Time Clock

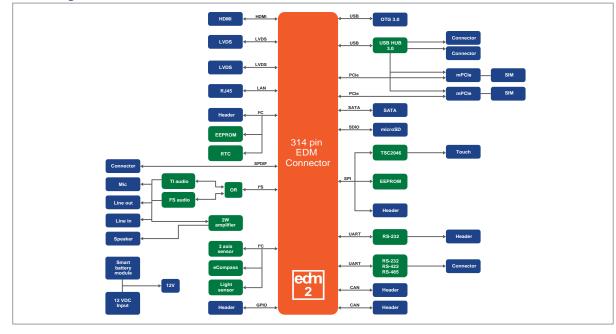
Power Specifications

Input power Battery 12 VDC Smart battery connector

4 **TechNexion** EDM Standard SOM's and Carrier Boards

EDM2-ELF

Block Diagram



Environmental and Mechanical Commercial : 0° to 60° C

Temperature

MTBF

Weight

Vibration

Shock

Humidity Module Connector Form Factor Dimensions

Industrial : -40° to 85° C 10 to 90% 314 pins MXM3 3.5" Form Factor 147 x 102 mm (5¾ x 4 inch) >100,000 hours 115 grams 50G / 25ms 20G / 0-600 Hz

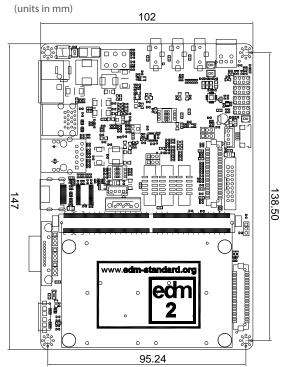
Extended : -20° to 70° C

Ordering Information EDM2-ELF

3.5 inch form factor Elf carrier board for EDM type 2 system-on-modules EDM2-ELF-START Elf EDM type 2 evaluation board including cablekit and adaptor

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions



EDM Standard SOM's and Carrier Boards

2015-05. All specifications are subject to change without notice.

EDM2-WIZARD



Main Features

- The official EDM type 2 Evaluation Carrier Board brings you a rich variety of interfaces and options at your fingertips.
- Wide range of jumper selectable audio, video and touch interfaces.
- Optional smart battery pack implementation.



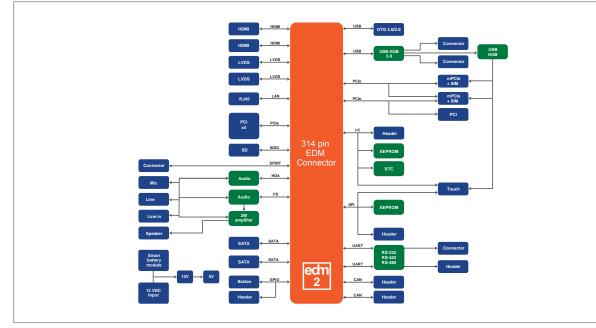
Power	LAN	LVDS	HDMI	PCle x4	SATA 2 nd	LPC	HDA	SPDIF	CANBus	SD	SPI	UART x2	Buttons	RSVD
5 VDC	LAN	LVDS	HDMI	PCle x2	SATA 1 st	USB OTG	USB Host	I ² S 1 st	x2	30	x2	l ² C x2	+ GPIO	RTC

Specifications

Core System		Video	
System on Module	EDM Type 2 compliant	Connector	2x HDMI
			2 channel LVDS 18/24 bit
Expansion			
Expansion Slots	2x mini-PCle + SIM cardslot	Audio	
	(for 3G communication)	Codec	Jumper selectable:
	1x PCle x1 expansion slot		Freescale SGTL5000 (I2S),
	(shared with mini-PCle)		TI TLV320AIC23B (I2S)
	1x PCle x4 expansion slot		Realtek ALC892-CG (HDA)
I/O Interfaces		Connector	5x 3.5 mm jack Surround audio S/PDIF
Connector	2x SATA	Speaker	2W amplified speaker connectors
	1x SD cardslot (SDIO)		
	1x Gigabit LAN	Touch	
	2x USB 3.0 Host	Controller	Jumper selectable:
	1x micro USB 3.0 / 2.0 OTG		TSC2046 (4 wire by SPI)
	1x UART (RS-232/422/485)		TSC2004 (4 wire by I2C)
Header	2x CAN Bus		ADS7845 (5 wire by SPI)
	1x UART (RS-232/422/485)		USB 4/5 wire touch controller
	2x SPI	Connector	4 wire touchpanel (USB/I2C/SPI)
	8x GPIO (shared with buttons)		5 wire touchpanel (USB/SPI)
	2x I ² C		
	Manufacturing pins	Power Specifica	ations
		Input Power	10~30 VDC
		Battery	Smart battery connector

EDM2-WIZARD

Block Diagram



Environmental and Mechanical

Temperature Humidity Module Connector Form Factor Dimensions

MTBF

Weight

Vibration

Shock

Commercial : 0° to 60° C 10 to 90% 314 pins MXM3 MicroATX Form Factor 244 x 244 mm 9% x 9% inch >100,000 hours 380 grams 50G / 25ms 20G / 0-600 Hz

Ordering Information

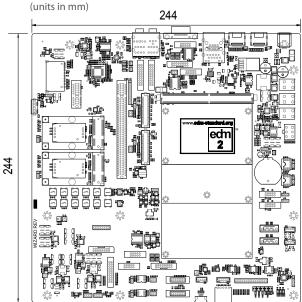
EDM2-WIZARD

MicroATX Form Factor Wizard Carrier Board for EDM Type 2 System on Modules EDM2-WIZARD-START

MicroATX Form Factor Wizard Carrier Board for EDM Type 2 System on Modules including cablekit and adaptor

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions



EDM Standard SOM's and Carrier Boards **TechNexion**

EDM ACCESSORIES

TDHJ070NA4RESKIT

• 7 inch touchscreen evaluation startkit

Pack content:

- LVDS-cable
- 4-wire touch cable
- 7" LCD display
 - * 1024x600 resolution
 - * 250 nits brightness
 - * 4 wire resistive touchscreen * dimensions 165.75 x 105.39 x 3.65 mm
- Adaptor PCB board







TDZJ070NAPCAPKIT

- 7 inch PCAP multi-touchscreen
 - Pack content:
- LVDS-cable
- USB interface cable
- 7" LCD display
 - * 1024x600 resolution
- * 500 nits brightness
- * PCAP touchscreen
- * dimensions 178 x 116 x 6.5 mm
- Adaptor PCB board



EDM ACCESSORIES

Heatspreaders



• EDMSPSC200501

- EDM Compact heat spreader
- 4 screws
- 20*20 mm thermopad 0.5 mm thickness

Passive heatsinks



• EDMHSCP12200501

- EDM Compact 12 mm passive heatsink + mylar
- 4 screws
- 4 washers
- 20*20 mm thermopad 0.5 mm thickness

Antenna kit



• EDMANTP150A138045D2450BK

- 4.5 dB, 2.4/5 GHz, black color antenna
- 15cm u.FL to SMA patch cable

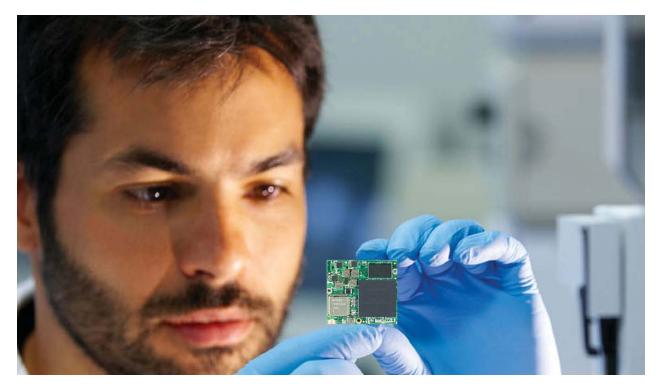
EDM Connector kit



• EDMCONNECTORKIT

- 10 EDM Connectors (AS0B821-S78B-7H)
- 40 M3 6mm mounting screws
- 40 mounting poses
 - 2015-05. All specifications are subject to change without notice.

PICO SERIES



About DWARF Platform

PICO System-on-Modules are Ubiquitous computing very compact high performance SoM's that are highly optimized for mobile Internet of Things applications using a pin-compatible scalable platform that not only utilize the "Edison" connector connectivity

" Putting huge things in tiny spaces "

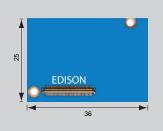
for sensors and low-speed I/O but also adds additional expansion possibilities for multimedia and connectivity.

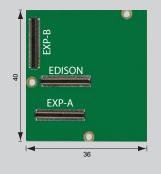
Additionally the "DWARF" platform eases proto-typing and accelerate time to market by offering a complete platform introducing

a large number of ready to use sensors and available I/O's to take advantage of todays' technology and communication challenges, giving our customers' cutting edge technology that can easily be expanded and implemented into Industry 4.0 applications.

DRONES	Compact and lightweight.
WEARABLES	Low power, small and easily expandable.
A PPLIANCES	Multimedia options and control I/O.
ROBOTICS	Camera and sensors. Battery powered.
FUN	Opensource softwareenough said.

Form Factors





PICO SERIES

Longevity

TechNexion PICO Modules incorporate only components from embedded roadmaps of strategic suppliers and are backed up with value added technical services such as life cycle management, revision control and end-of-life support.

TechNexion and Open Source

TechNexion PICO modules come standard with source code and binary demo images for the following Operating Systems.



Android binary demo images, instructions to make your own as well as complete source code available.



Linux binary demo images and full source code u-boot, kernel and support packages available.



yocto binary demo images and full source code u-boot, kernel and support packages available.



ubuntu binary demo images available.

Custom Carrier board Design

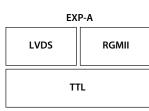
Customers can design their own carrier board using the freely available schematic design files and leverage on the available software source code that comes standard with every PICO Module and therefore bringing a custom designed solution to market using a very short design cycle and reduced engineering risks.

TechNexion offers custom tailored carrier board design and manufacturing services where our expertise will assist you to ensure your design is fully compatible and future upgrade proof while moving to next generation PICO modules.

Development Startkits

Kickstart your project development cycle with our plug and play development startkits that come pre-loaded with working software and all tools to assist you to validate performance and explore additional possibilities without the need to invest a huge amount of time and resources upfront.

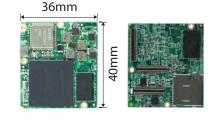
		EDISON		
Power	SDIO	l²S	SPI	PWM
3.3~4.5V	USB OTG	UART	I ² C	GPIO

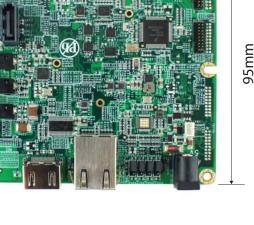


	EX	P-B	
CAN	PCle	HDMI	SATA
l²C	USB HOST	мі	PI

2015-05. All specifications are subject to change without notice.

95mm





TOUCAI

PICO

OVERVIEW









Model Name	PICO-iMX6-SD	PICO-iMX6-EMMC	PICO-iMX6POP-SD	PICO-iMX6POP-EMMC
Processor	i.MX6 Solo / Dualite	i.MX6 Solo / Dualite	i.MX6 Dual / Quad	i.MX6 Dual / Quad
Technology	ARM Cortex-A9 single/ dual core @ 1Ghz	ARM Cortex-A9 single/ dual core @ 1Ghz	ARM Cortex-A9 dual / quad @ 1Ghz	ARM Cortex-A9 dual / quad @ 1Ghz
PMIC			Freescale MMPF0100	Freescale MMPF0100
Memory	up to 2GB DDR3	up to 2GB DDR3	up to 2GB LPDDR2	up to 2GB LPDDR2
Storage	μ SD cardslot	eMMC	μ SD cardslot	eMMC
Network	RGMII	RGMII	RGMII	RGMII
Wireless LAN	802.11ac	802.11ac	802.11ac	802.11ac
Bluetooth	BT v. 4.0	BT v. 4.0	BT v. 4.0	BT v. 4.0
HDMI	\checkmark	\checkmark	\checkmark	✓
LVDS	\checkmark	\checkmark	\checkmark	\checkmark
ΠL	\checkmark	\checkmark	\checkmark	\checkmark
l²S	\checkmark	\checkmark	\checkmark	\checkmark
PCle	\checkmark	\checkmark	\checkmark	\checkmark
SATA			\checkmark	\checkmark
USB Host	\checkmark	\checkmark	\checkmark	\checkmark
USB OTG	\checkmark	\checkmark	\checkmark	\checkmark
SDIO	\checkmark	\checkmark	\checkmark	\checkmark
CAN Bus	\checkmark	\checkmark	\checkmark	\checkmark
SPI	\checkmark	\checkmark	\checkmark	✓
I ² C	\checkmark	\checkmark	\checkmark	\checkmark
GPIO	✓	\checkmark	\checkmark	\checkmark
Edison Signals	\checkmark	\checkmark	\checkmark	✓
Expansion Signals	\checkmark	\checkmark	\checkmark	✓
Dimensions	36 x 40 mm 1¾ x 1≸ inch	36 x 40 mm 1¾ x 1≸ inch	36 x 40 mm 1¾ x 1% inch	36 x 40 mm 1¾ x 1% inch

PICO System-on-Modules



PICO-iMX6UL
i.MX6UL
ARM Cortex-A7 single core @ 528Mhz
Freescale MMPF3000
up to 1GB DDR3
QSPI
RMII
802.11ac
BT v. 4.0
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
\checkmark
36 x 40 mm 1⅔ x 1% inch



PICO-DWARF	Model Name		
All	PICO module		
\checkmark	HDMI		
√	LVDS		
\checkmark	ΠL		
\checkmark	SATA		
\checkmark	MIPI DSI / CSI		
\checkmark	μ SD cardslot		
	Gigabit LAN		
\checkmark	USB host		
\checkmark	USB OTG		
\checkmark	UART		
\checkmark	CAN Bus		
\checkmark	SPI		
\checkmark	GPIO		
\checkmark	l ² C		
\checkmark	l²S		
\checkmark	Audio Codec		
\checkmark	Altimeter		
\checkmark	3D Accelerometer		
\checkmark	Gyroscope		
\checkmark	RTC		
5 VDC +/- 5%	Power		
\checkmark	Battery Charging Circuit		
\checkmark	Edison Connector		
✓	Expansion Connector		
95 x 95 mm 3¾ x 3¾ inch	Dimensions		

CORPORATE

2015-05. All specifications are subject to change without notice.

PICO System-on-Modules and DWARF Platform **TechNexion**

PICO-IMX6-SD



Main Features

- The PICO-IMX6-SD design based on the Freescale i.MX6 multimedia processor is a purpose-built, small footprint hardware platform compatible with Intel Edison baseboards and adds a number of additional high-speed signals such as PCIe, RGMII LAN, USB as well as 24 bit TTL Display, LVDS, HDMI and MIPI CSI Camera and MIPI DSI Display options.
- ARM Cortex-A9 Freescale i.MX6 scalable single/dual core System-on-Module
- WiFi 802.11ac and Bluetooth v. 4.0 communication interface

Vivante GC880

Open GL ES 2.0

Vivante GC320

600Mpxl/s, BLIT

1080p30 + D1

1080p30 H.264

BP / Dual 720p

I²S (1 channel)

On Carrier Board

35Mtri/s 266Mpxl/s

Emulated on GPU 3D



EX	Ρ-	в

		EDISON			
Power	SDIO	l²S	SPI	PWM	L
3.3~4.5V	USB OTG	UART	l ² C	GPIO	

EXP-A			
LVDS	RGMII		
T	TL		

EXF-D				
CAN	PCle	HDMI	SATA	
I ² C	USB HOST	MIPI		

Specifications

Core System

CPU Technology System Memory Storage

Connectivity

Network RGMII WiFi Bluetooth

I/O Interface Signalling

Edison I/O @ 1.8V

Additional I/O @ 3.3V

Freescale i.MX6 Solo / Duallite ARM Cortex-A9 single/dual core @ 1Ghz up to 2GB DDR3 Micro SD cardslot

Signals routed to connector Broadcom BCM4335 802.11ac Broadcom BCM4335 BT 4.0

9x GPIO

4x PWM 2x I²C 1x I²S 1x SPI 2x UART USB-OTG SDIO (4-bit) Single Channel LVDS 24-bit TTL RGB HDMI 1.4 MIPI CSI Camera **MIPI DSI Display** PCle RGMII (gigabit LAN) CAN USB Host

Video GPU 3D

GPU 2D (Vector Graphics)

GPU 2D (Composition) Video Decode Video Encode

Audio

Interface Audio Codec

Power Specifications 3.3 ~ 4.5 VDC

Input Power

Connectors

Board-to-Board

1x Edison compatible connector (Hirose 70-pin) 2x Hirose 70-pin connectors

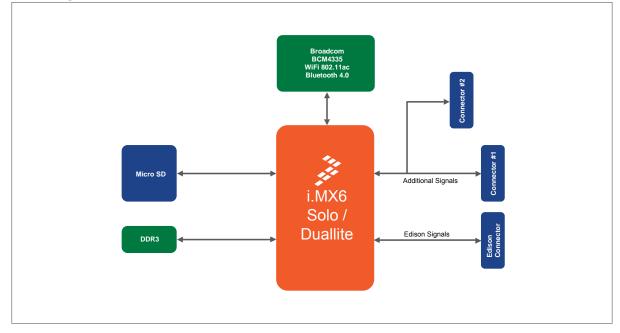
Operation Systems

Standard Support

Linux 3.x, Yocto, Android 4.3, Android 4.4, Android 5.0, Ubuntu

PICO-IMX6-SD

Block Diagram



Environmental and Mechanical

Commercial : 0° to 60° C

Extended : -20° to 70° C

10 to 90%

8 grams

50G / 25ms

36 x 40 mm

1% x 1% inch

>100,000 hours

20G / 0-600 Hz

Industrial : -40° to 85° C (no WiFi)

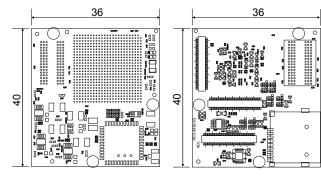
Temperature

Humidity Dimensions

MTBF Weight Shock Vibration

Dimensions

(units in mm)



Ordering Information PICOIMX6S10R512SD

Pico SoM Freescale i.MX6 Solo 1Ghz + 512MB RAM + SD Cardslot **PICOIMX6510R512SDBW** Pico SoM Freescale i.MX6 Solo 1Ghz + 512MB RAM + SD Cardslot + 802.11AC + Bluetooth 4.0 **PICOIMX6U10R1GBSD** Pico SoM Freescale i.MX6 Duallite 1Ghz + 1GB RAM + SD Cardslot **PICOIMX6U10R1GBSDBW** Pico SoM Freescale i.MX6 Duallite 1Ghz + 1GB RAM + SD Cardslot + 802.11AC + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.

35

2015-05. All specifications are subject to change without notice.

PICO-IMX6-EMMC



Main Features

- The PICO-IMX6-EMMC design based on the Freescale i.MX6 multimedia processor is a purpose-built, small footprint hardware platform compatible with Intel Edison baseboards and adds a number of additional high-speed signals such as PCIe, RGMII LAN, USB as well as 24 bit TTL Display, LVDS, HDMI and MIPI CSI Camera and MIPI DSI Display options.
- ARM Cortex-A9 Freescale i.MX6 scalable single/dual core System-on-Module
- WiFi 802.11ac and Bluetooth v. 4.0 communication interface



le	TT.		
		EXP-B	

_		EDISON			
	SDIO	l²S	SPI	PWM	
	USB OTG	UART	I ² C	GPIO	

EXP-A					
LVDS	RGMII				
п	Ľ				

EXP-B					
CAN	PCle	HDMI	SATA		
l²C	USB HOST	мі	PI		

Specifications

Core System

Power 3.3~4.5V

CPU Technology System Memory Storage

Connectivity

Network RGMII WiFi Bluetooth

I/O Interface Signalling

Edison I/O @ 1.8V

Additional I/O @ 3.3V

Freescale i.MX6 Solo / Duallite ARM Cortex-A9 single/dual core @ 1Ghz up to 2GB DDR3 Onboard eMMC (default 4GB)

Signals routed to connector Broadcom BCM4335 802.11ac Broadcom BCM4335 BT 4.0

9x GPIO 4x PWM 2x I²C 1x I²S 1x SPI 2x UART USB-OTG SDIO (4-bit) Single Channel LVDS 24-bit TTL RGB HDMI 1.4 MIPI CSI Camera MIPI DSI Dirplay

MIPI DSI Display PCle RGMII (gigabit LAN) CAN USB Host Video GPU 3D

GPU 2D

GPU 2D

(Vector Graphics)

(Composition)

Video Decode

Video Encode

Vivante GC880 35Mtri/s 266Mpxl/s Open GL ES 2.0

Emulated on GPU 3D

Vivante GC320 600Mpxl/s, BLIT 1080p30 + D1 1080p30 H.264 BP / Dual 720p

Audio

Interface Audio Codec

Power Specifications Input Power 3.3

ower 3.3 ~ 4.5 VDC

Connectors Board-to-Board

1x Edison compatible connector (Hirose 70-pin) 2x Hirose 70-pin connectors

Operation Systems Standard Support

Linux 3.x, Yocto, Android 4.3, Android 4.4, Android 5.0, Ubuntu

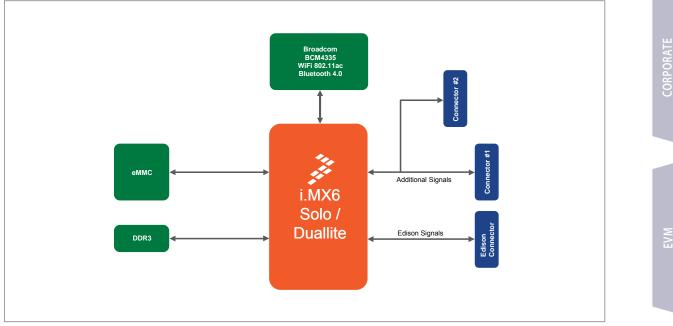
Vivante 600Mpx

1080 BP / [

> l²S (1 channel) On Carrier Board

PICO-IMX6-EMMC





Environmental and Mechanical

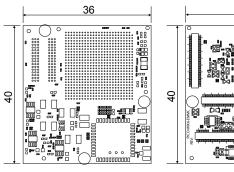
Temperature

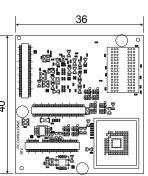
Humidity Dimensions

MTBF Weight Shock Vibration Commercial : 0° to 60° C Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 36 x 40 mm 1% x 1% inch >100,000 hours 8 grams 50G / 25ms 20G / 0-600 Hz

Dimensions

(units in mm)





Ordering Information PICOIMX6S10R512NI4G

Pico SoM Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB EMMC

PICOIMX6S10R512NI4GBW

Pico SoM Freescale i.MX6 Solo 1Ghz + 512MB RAM + 4GB EMMC + 802.11AC + Bluetooth 4.0

PICOIMX6U10R1GBNI4G

Pico SoM Freescale i.MX6 Duallite 1Ghz + 1GB RAM + 4GB EMMC

PICOIMX6U10R1GBNI4GBW

Pico SoM Freescale i.MX6 Duallite 1Ghz + 1GB RAM

+ 4GB EMMC + 802.11AC + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.

PICO-IMX6POP-SD



Main Features

- The PICO-IMX6POP-SD design based on the Freescale i.MX6 multimedia processor is a purpose-built, small footprint hardware platform compatible with Intel Edison baseboards and adds a number of additional high-speed signals such as PCIe, RGMII LAN, USB as well as 24 bit TTL Display, LVDS, HDMI and MIPI CSI Camera and MIPI DSI Display options.
- ARM Cortex-A9 Freescale i.MX6 scalable dual / quad core System-on-Module
- WiFi 802.11ac and Bluetooth v. 4.0 communication interface

Vivante GC2000

Open GL ES 2.0

& Halti, CL EP

300Mpxl/s

OpenVG 1.1

Vivante GC355

Vivante GC320

600Mpxl/s, BLIT

1080p60 H.264

1080p30 H.264

BP / Dual 720p

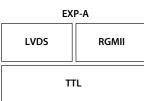
I²S (1 channel)

On Carrier Board

200Mtri/s 1000Mpxl/s



		EDISON		
Power	SDIO	l²S	SPI	PWM
3.3~4.5V	USB OTG	UART	l ² C	GPIO



EXP-B						
CAN	PCle	HDMI	SATA			
l²C	USB HOST	мі	PI			

Specifications

Core System

CPU Technology PMIC System Memory Storage

Connectivity

Gigabit Network RGMII WiFi Bluetooth

I/O Interface Signalling

Edison I/O @ 1.8V

Freescale i.MX6 Dual / Quad (PoP) ARM Cortex-A9 dual/quad core @ 1Ghz Freescale MMPF0100 up to 2GB LPDDR2 Micro SD cardslot

Broadcom BCM4335 802.11ac Broadcom BCM4335 BT 4.0

4x PWM 2x I²C

1x I²S

1x SPI 2x UART

USB-OTG SDIO (4-bit)

HDMI 1.4

Single Channel LVDS

24-bit TTL RGB

MIPI CSI Camera

9x GPIO

Additional I/O @ 3.3V

Signals routed to connector

GPU 2D

Video GPU 3D

(Vector Graphics) GPU 2D (Composition) Video Decode Video Encode

Audio

Interface Audio Codec

Power Specifications

Input Power 3.3 ~ 4.5 VDC

Connectors

Board-to-Board

Operation Systems Standard Support

Linux 3.x, Yocto, Android 4.3, Android 4.4, Android 5.0, Ubuntu

2x Hirose 70-pin connectors

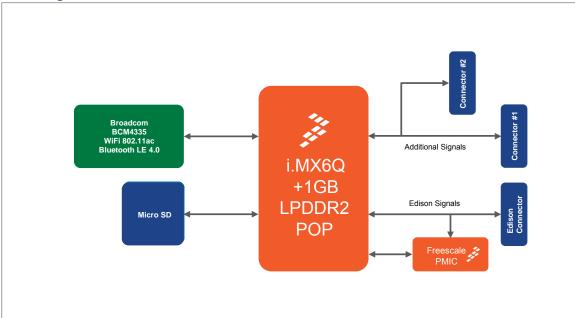
1x Edison compatible connector (Hirose 70-pin)

MIPI DSI Display PCle SATA II RGMII (gigabit LAN) Flex CAN version 2.0B Compliant **USB Host**

TechNexion PICO System-on-Modules and DWARF Platform

PICO-IMX6POP-SD





Environmental and Mechanical

Temperature

Humidity Dimensions

MTBF Weight Shock Vibration

Dimensions

Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 36 x 40 mm 1¾ x 15% inch >100,000 hours 8 grams 50G / 25ms 20G / 0-600 Hz

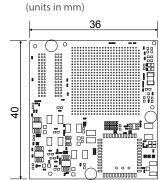
Commercial : 0° to 60° C

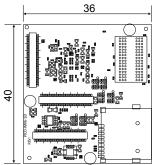
Ordering Information PICOIMX6QP10R1GBSDBW

Pico SoM Freescale with i.MX6 Quad PoP + 1GB LPDDR2 + SD Cardslot + 802.11AC + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.







PICO-IMX6POP-EMMC



Main Features

- The PICO-IMX6POP-EMMC design based on the Freescale i.MX6 multimedia processor is a purpose-built, small footprint hardware platform compatible with Intel Edison baseboards and adds a number of additional high-speed signals such as PCIe, RGMII LAN, USB as well as 24 bit TTL Display, LVDS, HDMI and MIPI CSI Camera and MIPI DSI Display options.
- ARM Cortex-A9 Freescale i.MX6 scalable dual / quad core System-on-Module
- WiFi 802.11ac and Bluetooth v. 4.0 communication interface



Vivante GC2000

Open GL ES 2.0

Vivante GC355

Vivante GC320

600Mpxl/s, BLIT

1080p60 H.264

1080p30 H.264

BP / Dual 720p

I²S (1 channel)

On Carrier Board

& Halti, CL EP

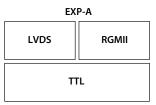
300Mpxl/s

OpenVG 1.1

200Mtri/s 1000Mpxl/s

9"			
	EX	P-B	
CAN	PCle	ндмі	SAT

		EDISON		
Power	SDIO	l²S	SPI	PWM
3.3~4.5V	USB OTG	UART	I ² C	GPIO



EXP-B					
CAN	PCle	HDMI	SAT		
l²C	USB HOST	МІ	PI		

Specifications

Core System

CPU Technology PMIC System Memory Storage

Connectivity

Gigabit Network RGMII WiFi Bluetooth

I/O Interface Signalling

Edison I/O @ 1.8V

Freescale i.MX6 Dual / Quad (PoP) ARM Cortex-A9 dual/guad core @ 1Ghz Freescale MMPF0100 up to 2GB LPDDR2 Onboard eMMC (default 4GB)

Signals routed to connector Broadcom BCM4335 802.11ac Broadcom BCM4335 BT 4.0

9x GPIO

Additional I/O @ 3.3V

2x I²C $1 \times l^2 S$ 1x SPI 2x UART USB-OTG SDIO (4-bit) Single Channel LVDS 24-bit TTL RGB HDMI 1.4 MIPI CSI Camera **MIPI DSI Display** PCle SATA II RGMII (gigabit LAN) Flex CAN version 2.0B Compliant USB Host

Video GPU 3D

GPU 2D (Vector Graphics)

GPU 2D (Composition) Video Decode Video Encode

Audio

Interface Audio Codec

Power Specifications

Input Power 3.3 ~ 4.5 VDC

Connectors Board-to-Board

1x Edison compatible connector (Hirose 70-pin) 2x Hirose 70-pin connectors

Operation Systems

Standard Support

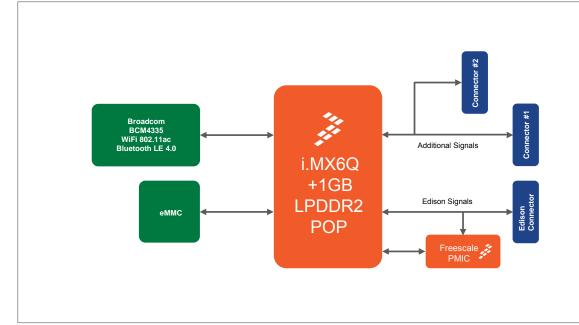
Linux 3.x, Yocto, Android 4.3, Android 4.4, Android 5.0, Ubuntu

40

4x PWM

PICO-IMX6POP-EMMC

Block Diagram



Environmental and Mechanical

Temperature

Humidity Dimensions

MTBF Weight Shock Vibration Commercial : 0° to 60° C Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 36 x 40 mm 1% x 1% inch >100,000 hours 8 grams 50G / 25ms 20G / 0-600 Hz

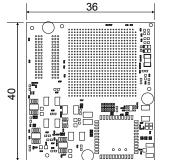
Ordering Information PICOIMX6QP10R1GBNI4GBW

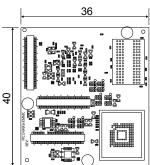
Pico SoM Freescale with i.MX6 Quad PoP + 1GB LPDDR2 + 4GB EMMC + 802.11AC + Bluetooth 4.0

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions

(units in mm)





TOUCAN

PICO-IMX6UL



EDISON

I²S

UART

SPI

I²C

Main Features

- The PICO-IMX6UL design based on the Freescale i.MX6 multimedia processor is a purpose-built, small footprint hardware platform compatible with Intel Edison baseboards and adds a number of additional high-speed signals such as RMII LAN, USB and 24 bit TTL Display
- ARM Cortex-A7 Freescale i.MX6UL single core System-on-Module
- WiFi 802.11ac and Bluetooth v. 4.0 communication interface



FX	Ρ-	R	

CAN	PCle	HDMI	SATA
I ² C	USB HOST	MI	PI

Image re-sizing, rotation, overlay and

CSC Pixel Processing Pipeline

I²S (2 channel), S/P DIF

on Carrier Board

3.3 ~ 4.5 VDC

Specifications

SDIO

USB

OTG

Core System

Power 3.3~4.5V

CPU Technology System Memory Storage Freescale i.MX6UL @ 528MHz ARM Cortex-A7 single core up to 1GB DDR3 QSPI (default 256MB)

Signals routed to connector

Broadcom BCM4335 BT 4.0

Broadcom BCM4335 802.11ac

PWM

GPIO

Connectivity

Network RMII WiFi Bluetooth

I/O Interface Signalling

Edison I/O @ 1.8V

Additional I/O @ 3.3V

9x GPIO 4x PWM 2x I²C 1x I²S 1x SPI 2x UART USB-OTG SDIO (4-bit) 24-bit TTL RGB RMII LAN CAN USB Host

Video

EXP-A

TTL

RMII

LVDS

PXP

Audio

Interface Audio Codec

Power Specifications

Input Power

Connectors Board-to-Board

1x Edison compatible connector (Hirose 70-pin) 2x Hirose 70-pin connectors

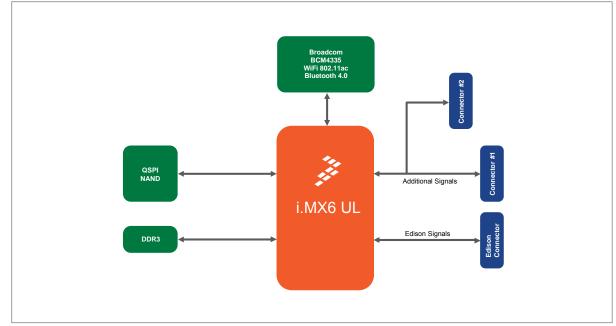
Operation Systems

Standard Support

Linux 3.x, Yocto

PICO-IMX6UL

Block Diagram



Environmental and Mechanical

Temperature

Humidity Dimensions

MTBF Weight Shock Vibration

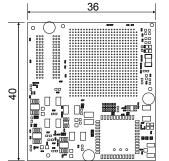
Commercial : 0° to 60° C Extended : -20° to 70° C Industrial : -40° to 85° C (no WiFi) 10 to 90% 36 x 40 mm 1¾ x 1% inch >100,000 hours 8 grams 50G / 25ms 20G / 0-600 Hz

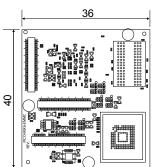
Ordering Information TBD

PICO System-on-Modules and DWARF Platform

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions (units in mm)





TechNexion

PICO

PICO-DWARF



Main Features

- The PICO-DWARF reference design is compatible with Intel Edison and TechNexion Pico SoM modules and add a variety of sensors and connectivity to the Pico SoM making it the ideal candidate for IoT (Internet of Things) applications such as drones, wearables, appliances and robotics.
- The complete schematics, design files, board files and BOM lists of PICO-DWARF are available and can be downloaded from the TechNexion homepage.



HDMI connector

Freescale SGTL5000

	EXI	P-B	
N	DCIa		

EDISON					
Power	SDIO	l ² S	SPI	PWM	
3.3~4.5V	USB OTG	UART	l ² C	GPIO	

EXP-A			
LVDS	RGMII		
Т	ſL		

EXP-B				
CAN	PCIe HDMI SATA			
l²C	USB HOST	MIPI		

Specifications

Core System

System-on-Module

Connectivity

Network Connector

Expansion

Storage

USB

Expansion Pin Headers

Compatible with Intel Edison connector (1x 70-pin Hirose Connector) Compatible with TechNexion Pico connectors (3x 70-pin Hirose Connector)

Atheros AR8031 Gigabit LAN **RJ-45 LAN Connector**

1x SATA data + power connector 1x micro SD cardslot 1x USB 2.0 Host connector 1x USB 2.0 OTG connector Single Channel LVDS 24-bit TTL RGB PCle CAN GPIO PWM I²C SPI UART

Video **External Display** Internal Display

Camera

Audio

Audio Codec Audio Connectors

Power Specifications

Input Power **Power Connector** Battery Charging Circuit

Battery Connector

Sensors

Altimeter 3D Accelerometer Gyroscope RTC

5 VDC +/- 5% 5.5 / 2.1mm barrel jack Freescale MC32BC3770CSR2 Single Cell Lipo Battery Charging Circuit 2 pin header

Single Channel LVDS (expansion header)

MIPI CSI signals on 33-pin FPC connector

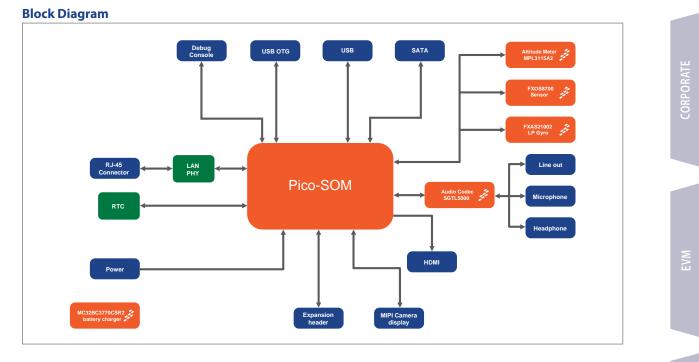
24-bit TTL RGB (expansion header) MIPI DSI Display on 33-pin FPC Connector

1x 3.5 mm jack Stereo Audio in

1x 3.5 mm jack Stereo Audio out 1x 3.5 mm jack Microphone

Freescale MPL3115A2 Freescale FXOS8700CQ Freescale FXAS21002 DS1337+ with backup battery

PICO-DWARF



Environmental and Mechanical

Temperature Humidity Dimensions

MTBF

Weight

Shock

Vibration

Commercial : 0° to 60° C 10 to 90% 95 x 95 mm 3¾ x 3¾ inch >100,000 hours 40 grams 50G / 25ms 20G / 0-600 Hz

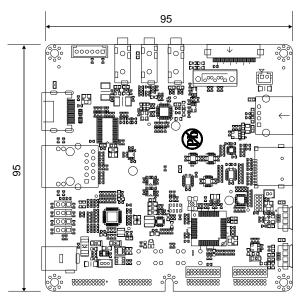
Ordering Information PICODWARF

PICO-DWARF Baseboard for PICO-SOM

* Feel free to contact us for custom tailored Carrier Board request for your projects.

Dimensions

(units in mm)



2015-05. All specifications are subject to change without notice.

TOUCAN SERIES



About TOUCAN

The Toucan series is a highly crafted product that can be deployed in not only industrial harsh environments but also in cosmetic savvy domotica applications utilizing its' versatile arsenal of industrial high-speed communication and control interfaces and optional wireless communication interfaces.

Standard the Toucan Series comes with wide voltage power inputs and Power over Ethernet, making the product suitable to be embedded into OEM/ODM end equipment.

Operation systems



Android runtime images, instructions to make your own as well as complete source code available.



Linux runtime images and full source code u-boot, kernel and support packages available.

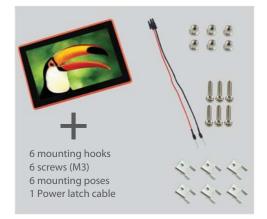


 yocto runtime images and full source code u-boot, kernel and support packages available.



ubuntu runtime images available.

Package content



Accessories



TOUCAN SERIES



HUMAN MACHINE INTERFACES

controlling your operations while saving on energy consumption and cooling



Product Overview

Model Name	TC0700	TC0720	ТС1000	TC1020
Screen size	7 inch	7 inch	10 inch	10 inch
Resolution	1024 x 600	1024 x 600	1280 x 800	1280 x 800
Luminance	500 cd/m ²	500 cd/m ²	350 cd/m ²	350 cd/m ²
CPU	i.MX6 Solo/Duallite	i.MX6 SoloX	i.MX6 Solo/Duallite/Dual/Quad	i.MX6 SoloX
Memory	Up to 2GB	Up to 2GB	Up to 2GB	Up to 2GB
storage	eMMC (4GB)	eMMC (4GB)	eMMC (4GB)	eMMC (4GB)
SD cardslot	μSD	μ SD	μSD	μSD
1 st LAN	802.3at POE	802.3at POE	802.3at POE	802.3at POE
2 nd LAN		\checkmark		\checkmark
WiFi	802.11bgn	802.11bgn	802.11bgn	802.11bgn
Bluetooth	BT v. 4.0	BT v. 4.0	BT v. 4.0	BT v. 4.0
HDMI	\checkmark		\checkmark	
USB OTG	\checkmark	\checkmark	\checkmark	\checkmark
USB Host	\checkmark	\checkmark	\checkmark	\checkmark
Serial	2	2	2	2
CAN Bus	2	2	2	2
GPIO	4	4	4	4
Input power	10~30V DC	10~30V DC	10~30V DC	10~30V DC
Audio (optional)	2W Stereo	2W Stereo	10W Stereo	10W Stereo
Weight	595 grams	595 grams	850 grams	850 grams
Dimensions (mm)	184 (W) x 122 (H) x 30 (D)	184 (W) x 122 (H) x 30 (D)	249 (W) x 168 (H) x 40 (D)	249 (W) x 168 (H) x 40 (D)







2015-05. All specifications are subject to change without notice.

Panel Computing **TechNexion**









7. RS-XXX

8. micro SD cardslot 9. USB 3.0 OTG 10. S1 Boot Select Button

11. Reset Button

Main Features

- Based around Freescale i.MX6 ARM Cortex-A9 multicore technology.
- Projective Multi-touch bright (500 nits) high resolution (1024 x 600) 7 inch panel.
- Galvanic isolated CAN Bus and serial ports (RS-232/422/485).
- USB host, USB OTG, Micro-SD cardslot, 4 GPIO's and HDMI for secondary display.
- Gigabit POE function or 10~30VDC power input.
- Available with colorful bezels.



Specifications

Core System Processor

Memory Storage

Freescale i.MX6 Solo/Duallite (i.MX6 Dual/Quad on project base) up to 2GB eMMC (4GB)

Connectivity

LAN	RJ-45 Gigabit Ethernet (POE function 802.3at)
WiFi	Broadcom BCM4330 802.11bgn
Bluetooth	Broadcom BCM4330 BT 4.0
External Display	HDMI 1.4
USB	1x USB Host 2.0 Connector
	1x USB OTG 3.0 Connector
SD cardslot	micro SD cardslot
Serial	1x RS-232 (galvanic isolated)
	1x RS-232/422/485 (galvanic isolated)
CAN Bus	2x Flex CAN version 2.0B Compliant
	(galvanic isolated)
GPIO	4x GPIO
Buttons	1x Reset button
	1x Boot select button (force SD card boot)
Power	2 pin DC power terminal block (10~30VDC)

Internal Expansion Interfaces

USB Audio 2x Internal pinheader Optional

Video GPU 3D

GPU 2D(Vector Graphics) GPU 2D (Composition) Video Decode Video Encode

Vivante GC880 35Mtri/s 266Mpxl/s Open GL ES 2.0 emulated on GPU 3D Vivante GC320 600Mpxl/s, BLIT 1080p30 + D1 1080p30 H.264 BP / Dual 720p

Display and Touch

Internal Screen Resolution Maximum Colors Luminance Touchscreen External Display

7 inch widescreen LCD display with LED backlight 1024 x 600 pixels 16.7 million 500 cd/m² Projective Capacitive multitouch HDMI 1.4 Connector

802.3at POE implementation (36~57VDC)

Power Specifications

Input Power Power over Ethernet

Power Consumption

Operation Systems Standard Support

Extended Support

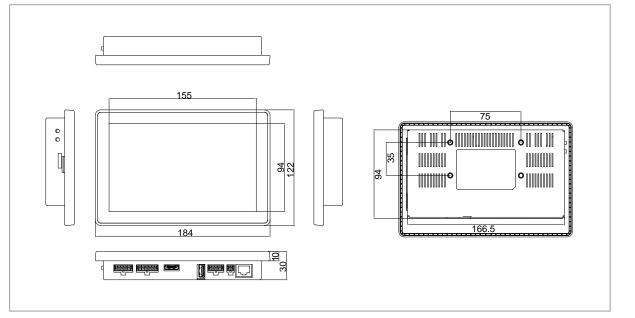
Linux Android Commercial Linux Windows Embedded Compact Real Time OS

10~30V DC +/- 5%

7 Watt

Dimensions

(units in mm)



Environmental and Mechanical Temperature

Humidity Dimensions MTBF Weight Shock Vibration Certification Commercial : 0° to 50° C Extended : -20° to 70° C 10 to 90% 184 (W) x 122 (H) x 30 (D) mm 50,000 hours 595 grams 50G / 25 ms 20G / 0-600 Hz Compliant with CE, FCC, RoHS, REACh directives

Mounting Options

Rear Mounting **VESA** Mounting 6 mounting clips required (included) 35*75 VESA MIS C. Standard (seperate purchase)

Ordering Information TC0700P6SR512NI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Solo TC0700PIBW6SR512NI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Solo with BT/WIFI Internal Antenna

TC0700PEBW6SR512NI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Solo with BT/WIFI External Antenna

TC0700P6UR1GBNI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Duallite TC0700PIBW6UR1GBNI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Duallite

with BT/WIFI Internal Antenna TC0700PEBW6UR1GBNI4Gxx

7 inch POE HMI PCAP Touch with Freescale i.MX6 Duallite with BT/WIFI External Antenna

* Replace xx with the desired color code below.

Color codes:

BL	Blue	GN	Green
BK	Black	RD	Red
YL	Yellow	OR	Orange
WT	Ivory White	GY	Gray

* Custom configurations possible.







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Panel Computing









1. PoE LAN 2. Power 3. GPIO x 4 4. USB2.0 5. 2nd LAN 6. CAN Bus 7. RS-XXX 8. micro SD cardslot 9. USB 3.0 OTG

10. S1 Boot Select Button 11. Reset Button

Main Features

- Based around Freescale i.MX6 SoloX Cortex-A9 Single core + ARM Cortex M4
- Projective Multi-touch bright (500 nits) high resolution (1024 x 600) 7 inch panel.
- Galvanic isolated CAN Bus and serial ports (RS-232/422/485).
- USB host, USB OTG, Micro-SD cardslot, 4 GPIO's
- Gigabit POE function or 10~30VDC power input.
- Available with colorful bezels.



Specifications

Core System

Processor Freescale i.MX6 SoloX Memory up to 2GB Storage eMMC (4GB) QSPI (default 256MB) optional NAND Flash (MOQ apply)

Connectivity

LAN	RJ-45 Gigabit Ethernet (POE function 802.3at)
2 nd LAN	Gigabit LAN
WiFi	Broadcom BCM4330 802.11bgn
Bluetooth	Broadcom BCM4330 BT 4.0
USB	1x USB Host 2.0 Connector
	1x USB OTG 3.0 Connector
SD cardslot	micro SD cardslot
Serial	1x RS-232 (galvanic isolated)
	1x RS-232/422/485 (galvanic isolated)
CAN Bus	2x Flex CAN version 2.0B Compliant
	(galvanic isolated)
GPIO	4x GPIO
Buttons	1x Reset button
	1x Boot select button (force SD card boot)
Power	2 pin DC power terminal block (10~30VDC)

Internal Expansion Interfaces

USB	2x Internal pinheader
Audio	Optional

Video GPU 3D

PXP

Vivante GC400T 17Mtri/s 133Mpxl/s Open GL ES 2.0 Image re-sizing, rotation, overlay and CSC Pixel Processing Pipeline

Display and Touch Internal Screen

Resolution Maximum Colors Luminance Touchscreen 7 inch widescreen LCD display with LED backlight 1024 x 600 pixels 16.7 million 500 cd/m² Projective Capacitive multitouch

Power Specifications

Input Power Power over Ethernet Power Consumption 10~30V DC +/- 5% 802.3at POE implementation (36~57VDC) 7 Watt

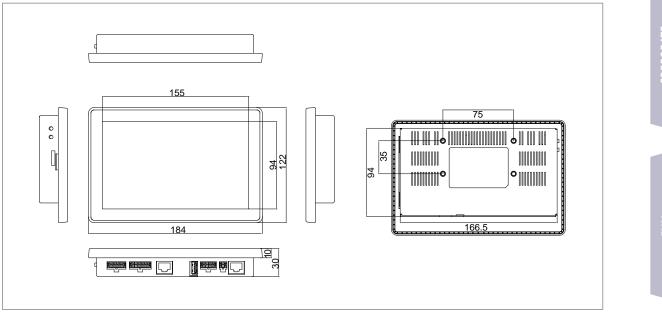
Operation Systems Standard Support

Extended Support

Linux Android Commercial Linux Windows Embedded Compact Real Time OS

Dimensions

(units in mm)



Environmental and Mechanical

Temperature Humidity

Dimensions

MTBF

Weight

Shock

Vibration

Certification

Commercial : 0° to 50° C Extended : -20° to 70° C 10 to 90% 184 (W) x 122 (H) x 30 (D) mm 50,000 hours 595 grams 50G / 25 ms 20G / 0-600 Hz Compliant with CE, FCC,

Mounting Options

Rear Mounting VESA Mounting RoHS, REACh directives

6 mounting clips required (included)

35*75 VESA MIS C. Standard (seperate purchase)

Ordering Information

TC0720P6X1GBNI4Gxx 7 inch POE HMI PCAP Touch with Freescale i.MX6 SoloX TC0720PIBW6X1GBNI4Gxx 7 inch POE HMI PCAP Touch with Freescale i.MX6 SoloX with BT/WIFI Internal Antenna TC0720PEBW6X1GBNI4Gxx 7 inch POE HMI PCAP Touch with Freescale i.MX6 SoloX with BT/WIFI External Antenna

* Replace xx with the desired color code below.

Color codes:

BL	Blue	GN	Green
BK	Black	RD	Red
YL	Yellow	OR	Orange
WT	Ivory White	GY	Gray

* Custom configurations possible.



TechNexion Panel Computing



Main Features

- Based around Freescale i.MX6 ARM Cortex-A9 multicore technology.
- Projective Multi-touch bright (500 nits) high resolution (1280 x 800) 10 inch panel.
- Galvanic isolated CAN Bus and serial ports (RS-232/422/485).
- USB host, USB OTG, Micro-SD cardslot, 4 GPIO's and HDMI for secondary display.
- Gigabit POE function or 10~30VDC power input.
- Available with colorful bezels.



Specifications

Core System

Processor Freescale i.MX6 Solo/Duallite/Dual/Quad Memory up to2GB DDR3 eMMC (4GB) Storage

Connectivity

LAN	RJ-45 Gigabit Ethernet (POE function 802.3at)
WiFi	Broadcom BCM4330 802.11bgn
Bluetooth	Broadcom BCM4330 BT 4.0
External Display	HDMI 1.4
USB	1x USB Host 2.0 Connector
	1x USB OTG 3.0 Connector
SD cardslot	micro SD cardslot
Serial	1x RS-232 (galvanic isolated)
	1x RS-232/422/485 (galvanic isolated)
CAN Bus	2x Flex CAN version 2.0B Compliant
	(galvanic isolated)
GPIO	16 x GPIO
Buttons	1x Reset button
	1x Boot select button (force SD card boot)
Power	2 pin DC power terminal block (10~30VDC)

Internal Expansion Interfaces

USB Audio 2x Internal pinheader Optional

Video				
	Solo / Duallite	Dual / Quad		
GPU 3D	Vivante GC880	Vivante GC2000		
	35Mtri/s 266Mpxl/s	200Mtri/s 1000Mpxl/s		
	Open GL ES 2.0	OpenGL ES 2.0		
		& Halti, CL EP		
GPU 2D(Vector Graphics)	emulated on GPU 3D	Vivante GC355		
		300Mpxl/s		
		OpenVG 1.1		
GPU 2D	Vivante GC320	Vivante GC320		
(Composition)	600Mpxl/s, BLIT	600Mpxl/s, BLIT		
Video Decode	1080p30 + D1	1080p60 H.264		
Video Encode	1080p30 H.264	1080p30 H.264		
	BP / Dual 720p	BP / Dual 720p		
Display and Touch				
Internal Screen	10 inch widescreen LCD display with			

Resolution Maximum Colors Luminance Touchscreen

vith LED backlight 1280 x 800 pixels 16.7 million 350 cd/m² Projective Capacitive multitouch

802.3at POE implementation (36~57VDC)

Power Specifications

Input Power Power over Ethernet Power Consumption

Operation Systems

Standard Support

Extended Support

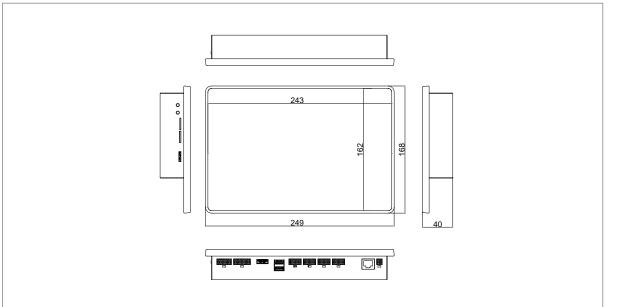
Linux Android Commercial Linux Windows Embedded Compact Real Time OS

10~30V DC +/- 5%

7 Watt

Dimensions

(units in mm)



Environmental and Mechanical

Temperature

Humidity Dimensions MTBF Weight Shock Vibration Certification Commercial : 0° to 50° C Extended : -20° to 70° C 10 to 90% 249 (W) x 168 (H) x 40 (D) mm 50,000 hours 850 grams 50G / 25 ms 20G / 0-600 Hz Compliant with CE, FCC, RoHS, REACh directives

Mounting Options

Rear Mounting VESA Mounting 6 mounting clips required (included) 35*75 VESA MIS C. Standard (seperate purchase)

Ordering Information

TBD

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Color codes:

BL	Blue	GN	Green
BK	Black	RD	Red
YL	Yellow	OR	Orange
WT	Ivory White	GY	Gray

* Custom configurations possible.



2015-05. All specifications are subject to change without notice.
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Main Features

- Based around Freescale i.MX6 SoloX Cortex-A9 Single core + ARM Cortex M4
- Projective Multi-touch bright (500 nits) high resolution (1280 x 800) 10 inch panel.
- Galvanic isolated CAN Bus and serial ports (RS-232/422/485).
- USB host, USB OTG, Micro-SD cardslot, 4 GPIO's
- Gigabit POE function or 10~30VDC power input.
- Available with colorful bezels.



Specifications

Core System

Processor Freescale i.MX6 SoloX + M4 Memory up to 2GB Storage eMMC (4GB) QSPI (default 256MB) optional NAND Flash (MOQ apply)

Connectivity

LAN	RJ-45 Gigabit Ethernet (POE function 802.3at)
2 nd LAN	Gigabit LAN
WiFi	Broadcom BCM4330 802.11bgn
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GPIO	16 x GPIO
Buttons	1x Reset button
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Power	2 pin DC power terminal block (10~30VDC)

Internal Expansion Interfaces

USB	2x Internal pinheader
Audio	Optional

Video

GPU 3D PXP Vivante GC400T 17Mtri/s 133Mpxl/s Open GL ES 2.0 Image re-sizing, rotation, overlay and CSC Pixel Processing Pipeline

Display and Touch

Internal Screen Resolution Maximum Colors Luminance Touchscreen 10 inch widescreen LCD display with LED backlight 1024 x 600 pixels 16.7 million 350 cd/m² Projective Capacitive multitouch

Power Specifications

Input Power Power over Ethernet Power Consumption 10~30V DC +/- 5% 802.3at POE implementation (36~57VDC) 7 Watt

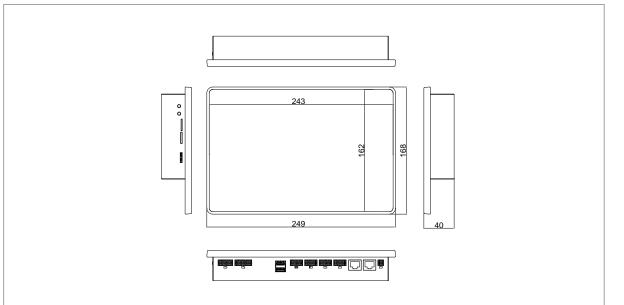
Operation Systems Standard Support

Extended Support

Linux Android Commercial Linux Windows Embedded Compact Real Time OS

Dimensions

(units in mm)



Environmental and Mechanical Temperature Commercial: 0°

Humidity Dimensions MTBF Weight Shock Vibration Certification Commercial : 0° to 50° C Extended : -20° to 70° C 10 to 90% 249 (W) x 168 (H) x 40 (D) mm 50,000 hours 850 grams 50G / 25 ms 20G / 0-600 Hz Compliant with CE, FCC, RoHS, REACh directives

Mounting Options

Rear Mounting VESA Mounting 6 mounting clips required (included) 35*75 VESA MIS C. Standard (seperate purchase)

Ordering Information TBD

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* Custom configurations possible.



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